



TG-NSP80 Non-Silicone Thermal Putty

REACH Compliant

OHS Compliant

Features

- · Thermal Conductivity 8.3 W/mK
- Easily dispensable from manual, semi-automatic or fully automatic systems
- · Not Electrically Isolating
- · Low thermal impedance
- · High thermal conductivity
- · Ultra-low compression forces
- · High tack on most surfaces and reworkable
- · Proven long term reliability

Applications

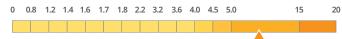
Consumer Electronics - Set-top boxes, IP routers, ECUs, Memory and Power modules

Standard Sizes

Syringe	Pot / Pail
30cc	0.45kg
55cc	2.2kg
	9kg
	36kg

Properties

Thermal Conductivity: 8.3 W/mK



Properties	TG-NSP80	Unit	Test Method
Thermal Conductivity	8.3	W/mK	ASTM D5470
Viscosity @ 25° C	1,400,000	1 sec⁻¹, cPs	-
Colour	Grey	-	Visual
Flow Rate (30cc syringe, 0.08" orifice at 50psi @ 25° C)	0.5 - 1.5	g/min	T-Global
Specific Gravity	2.3	-	ASTM D-70
Maximum Bond Thickness	0.013	mm	T-Global
Operating Temperature Range	-55~+200	° C	T-Global
Bleed @ 200° C, 24 hours	0.3	%/Wt	ASTM 6814
Evaporation @ 150° C, 24 hours	0.2	%/Wt	ASTM 6814
Shelf Life	60	months	T-Global

For full turn-key support, including design, testing, supply and installation of dispensing systems suitable for prototyping to fully automated volume production, please contact T-Global Technology.

T-Global Technology (Europe & North America) Limited

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T-Global Technology are proud to announce the launch of a new company logo and mission statement as part of the ongoing growth and evolution of our company's brand.

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NOTICE: The information contained herein is to the best of our knowledge true and accurate. Values stated in this technical data sheet represent typical values as not all tests are run on each lot of material